

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7	(("6433285") or ("6591494") or ("6031724") or ("20020027274") or ("6076737") or ("6780668") or ("5866950")).PN.	US-PGPUB ; USPAT	OR	OFF	2005/07/27 08:56
L2	4194	(chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1)	US-PGPUB ; USPAT; USOCR	OR	OFF	2005/07/27 09:00
L3	1186	(chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3)	US-PGPUB ; USPAT; USOCR	OR	OFF	2005/07/27 09:02
L4	546	(chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) with (seal\$3 encapsulat\$3 encas\$3 mould\$3)	US-PGPUB ; USPAT; USOCR	OR	OFF	2005/07/27 09:03
L5	14	(chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) with (seal\$3 encapsulat\$3 encas\$3 mould\$3) with (card\$1 tag\$1)	US-PGPUB ; USPAT; USOCR	OR	OFF	2005/07/27 09:15

L6	8	(chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) with (seal\$3 encapsulat\$3 encas\$3 mould\$3) with (card\$1 tag\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/27 09:16
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